

METHOD AND SYSTEM FOR ASSEMBLING A PRINTED CIRCUIT
BOARD USING A LAND GRID ARRAY

ABSTRACT OF THE DISCLOSURE

A device for assembling circuit boards. The device has an upper
5 surface for receiving a compressing force. The device also has a lower
surface for compressing a number of compression devices in a land grid
array assembly while allowing access to a number of fasteners associated
with the compression devices. The device is able to assist in the formation
of an electrical contact between a chip package in the land grid array
10 assembly and a circuit board by the lower surface being pressed against
the compression devices to compress the compression devices and then
allowing the plurality of fasteners to be tightened.

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